

The IBF-200 is a plant for nano-meter exact correction of small to medium sized optical surfaces. In the 200-S configuration it is possible to process substrates with a contact angle up to 90°. Beside this direct ion beam smoothing and reactive etching can be performed on this plant, too. This makes it most interesting for institutes and universities.



TECHNICAL DATA

WORK PIECE DATA

Diameter:	Ø5 mm – Ø200 mm (Ø0.2" – Ø2.75")
Thickness:	100 mm (4")
Weight:	max. 10 kg (22 lbs)
Contact angle:	max. 63° (standard version) max. 90° (type 200-5)
Shape:	plane, spherical, aspherical, freeform

SINGLE LOAD LOCK SYSTEM

Loading time:	< 2 min.
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AXIS SYSTEM

Type: 200-3	X, Y, Z, A
Type: 200-S	X, Y, Z, A, B
Travel:	X = 400 mm Y = 400 mm Z = 400 mm A ± 45° B = continuous

DIMENSIONS

Weight:	2450 kg (5390 lbs)
WxHxD:	3.75 m x 2.2 m x 1.7 m (148" x 87" x 67")
Footprint:	5.75 m x 3.7 m (226" x 146")

IBF200

